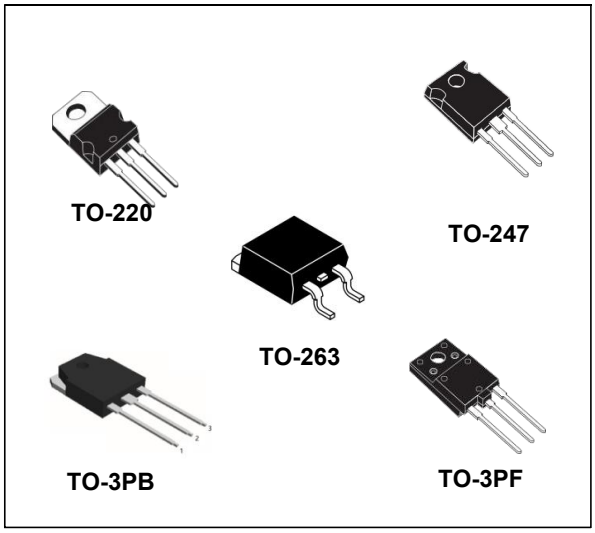
MS4N1350 MS4N1350E MS4N1350B MS4N1350W MS4N1350FW

N-channel 1500 V, 6 Ω, 4 A, Power MOSFET in TO-263,TO-247TO-220, TO-3PB, TO-3PF

Features

Type	V_{DSS}	R_{DS}(on) max.	I_D	P_{TOT}
MS4N1350FW	1500 V	< 9 Ω	4 A	63 W
MS4N1350	1500 V	< 9 Ω	4 A	140 W
MS4N1350B	1500 V	< 9 Ω	4 A	140 W
MS4N1350E	1500 V	< 9 Ω	4 A	80 W
MS4N1350W	1500 V	< 9 Ω	4 A	140 W



- 100% avalanche tested
- Intrinsic capacitances and Q_g minimized
- High speed switching
- Fully isolated TO-3PF plastic package
- Creepage distance path is 5.4 mm (typ.)for TO-3PF

Application

Switching applications

Description

MasPower has designed an advanced family of very high voltage Power MOSFETs with outstanding performances. The strengthened layout coupled with the company's proprietary edge termination structure, gives the lowest $R_{DS(on)}$ per area, unrivalled gate charge and switching characteristics.

Figure 1. Internal schematic diagram

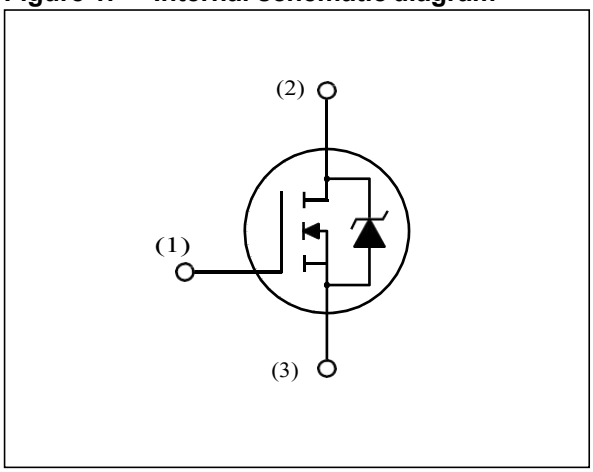


Table 1. Device summar

Order codes	Marking	Package	Packaging
MS4N1350	MS4N1350	TO-3PF	Tube
MS4N1350FW	MS4N1350FW	TO-220	Tube
MS4N1350E	MS4N1350E	TO-263	Tube
MS4N1350B	MS4N1350B	TO-3PB	Tube
MS4N1350W	MS4N1350W	TO-247	Tube

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-220,TO-247	TO-3PF	
V_{DS}	Drain-source voltage (V_{GS} = 0)	1500		V
V_{GS}	Gate-source voltage	± 30		V
I_D	Drain current (continuous) at T_C = 25 °C	4	4(1)	A
I_D	Drain current (continuous) at T_C = 100 °C	2.6	2.6 (1)	A
I_{DM} (1)	Drain current (pulsed)	10	10 (1)	A
P_{TOT}	Total dissipation at T_C = 25 °C	140	63	W
V_{ISO}	Insulation with stand voltage (RMS) from all three leads to external heat sink (t=1 s;T_C=25 °C)		3500	V
	Derating factor	1.12	0.5	W/°C
T_{stg}	storage temperature	-50 to 150		°C
T_j	Max. operating junction temperature	150		°C

1. Pulse width limited by safe operating area

Table 3. Thermal data

Symbol	Parameter	TO-220	TO-247	TO-263	TO-3PF	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case max	0.89		0.63	2	°C/W
$R_{thj\text{-}amb}$	Thermal resistance junction-ambient max	63.5	50	35	50	°C/W
T_j	Maximum lead temperature for soldering purpose	300				°C

Table 4. Avalanche characteristics

Symbol	Parameter	Max value	Unit
I_{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_j max)	4	A
E_{AS}	Single pulse avalanche energy (starting T_j = 25 °C, I_D = I_{AR}, V_{DD} = 50 V)	450	mJ

2 Electrical characteristics

(T_{case} = 25 °C unless otherwise specified)

Table 5. On /off states

Symbol	Parameter	Testconditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 1 mA, V_{GS} = 0	1500			V
I_{DSS}	Zero gate voltage	V_{DS} = Max rating			10	µA
	drain current (V = 0)	V = Max rating, T =125 °C			500	µA
I_{GSS}	Gate-body leakage current (V_{DS} = 0)	V_{GS} = ± 30 V			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	3	4	5	V
$R_{DS(on}$	static drain-source on resistance	V_{GS} = 10 V, I_D = 1.3 A		6	9	Ω

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
g_{fs} (1)	Forward transconductance	V_{DS} = 30 V, I_D = 1.3 A	-	2.6	-	S
C_{iss}	Input capacitance	V_{DS} = 25 V, f = 1 MHz, V_{GS} = 0	-	939	-	pF
C_{oss}	Output capacitance			102		pF
C_{rss}	Reverse transfer capacitance			13.2		pF
$C_{oss\ eq.}$ (2)	Equivalent output capacitance	V_{DS}=0 to 1200 V, V_{GS} = 0	-	100	-	pF
R_g	Gate input resistance	f=1 MHz Gate DC Bias=0 Test signal level=20 mV open drain	-	4	-	Ω
Q_g	Total gate charge	V_{DD} = 1200 V, I_D = 4 A, V_{GS} = 10 V *(see Figure 19)*	-	29.3	-	nC
Qgs	Gate-source charge			4.6		nC
Qgd	Gate-drain charge			17		nC

1. Pulsed: Pulse duration = 300 µs, duty cycle 1.5%
2. $C_{oss\ eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 7. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V = 750 V, I = 1.25 A, R_G = 4.7 Ω, V_{GS} = 10 V *(see Figure 18)*		24		ns
tr	Rise time			47		ns
td(off)	Turn-off-delay time		-	45	-	ns
tf	Fall time			61		ns

Table 8. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current				4	A
I_{SDM} (1)	Source-drain current (pulsed)		-		10	A
V_{SD} (2)	Forward on voltage	I_{SD} = 4 A, V_{GS} = 0	-		1.6	V
t_{rr}	Reverse recovery time	I_{SD} = 4 A, di/dt = 100 A/µs		410		ns
Qrr	Reverse recovery charge	V_{DD}= 60 V		2.4		µc
IRRM	Reverse recovery current	*(see Figure 20)*	-	11.7		A
t_{rr}	Reverse recovery time	I_{SD} = 4 A, di/dt = 100 A/µs		540		ns
Qrr	Reverse recovery charge	V_{DD}= 60 V, Tj = 150 °C		3.3		µc
IRRM	Reverse recovery current	*(see Figure 20)*	-	12.3		A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300 µs, duty cycle 1.5%

2.1 Electrical characteristcs (curves)

Figure 2. Safe operating area for TO-3PF

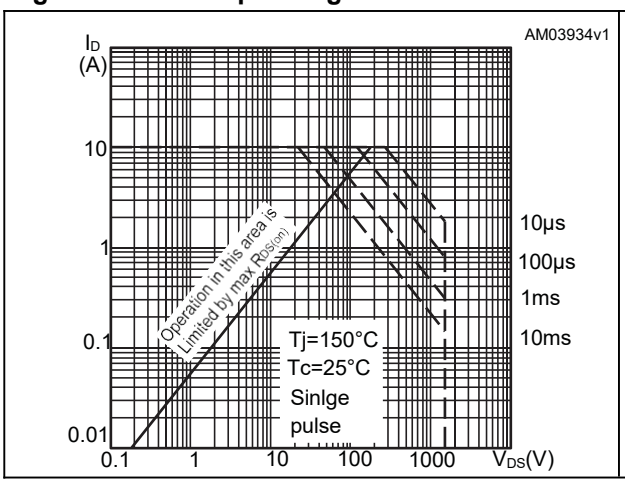


Figure 3. Thermal impedance for TO-3PF

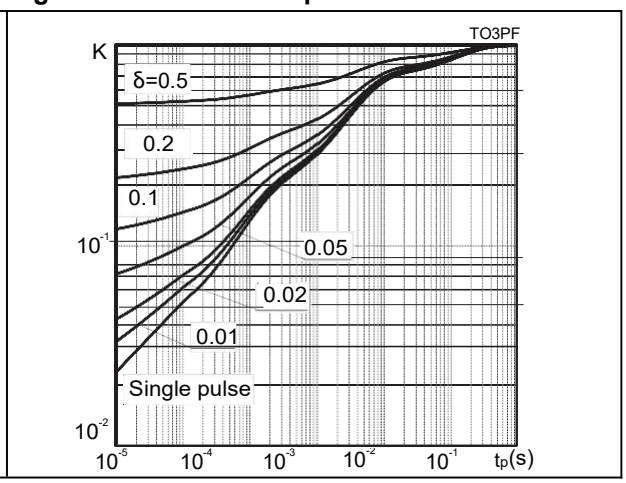


Figure 4. Safe operating area for TO-220

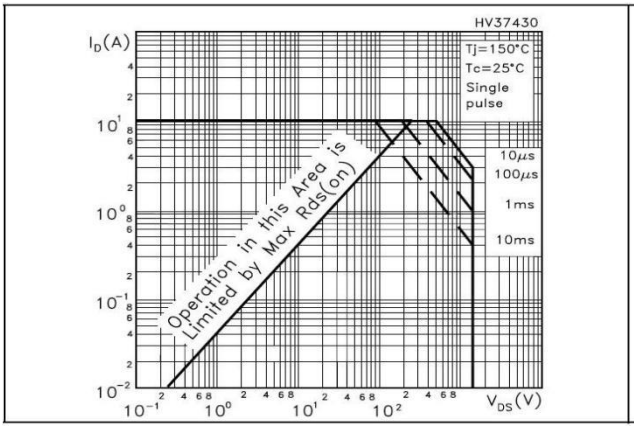


Figure 5. Thermal impedance for TO-220

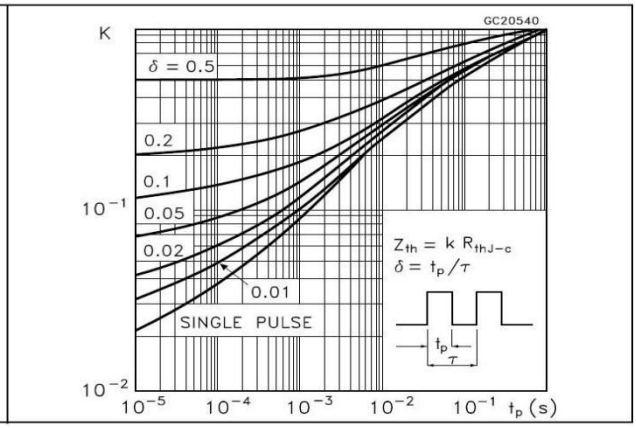


Figure 6. Safe operating area for TO-247

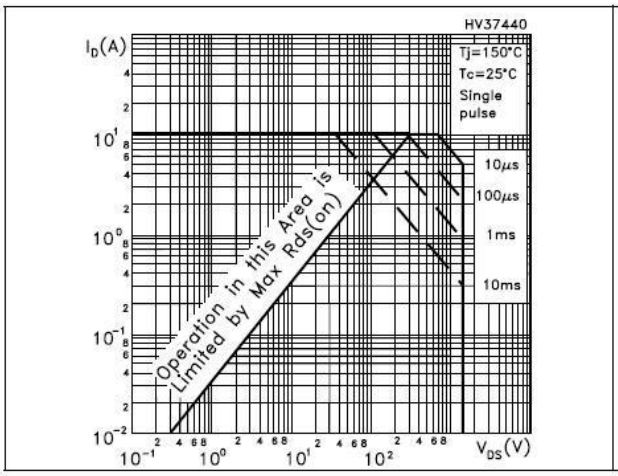


Figure 7. Thermal impedance for TO-247

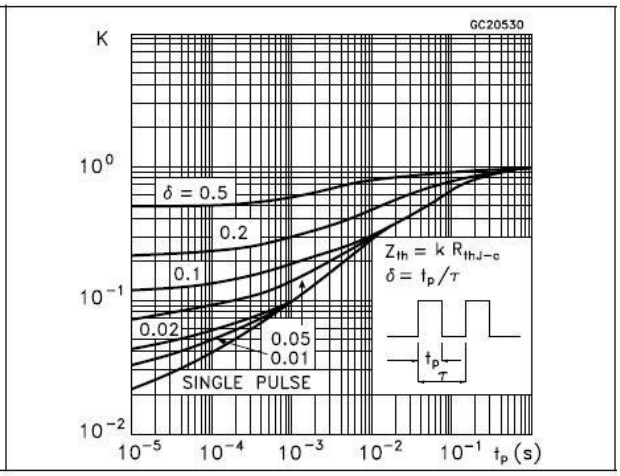


Figure 8. Output characteristics

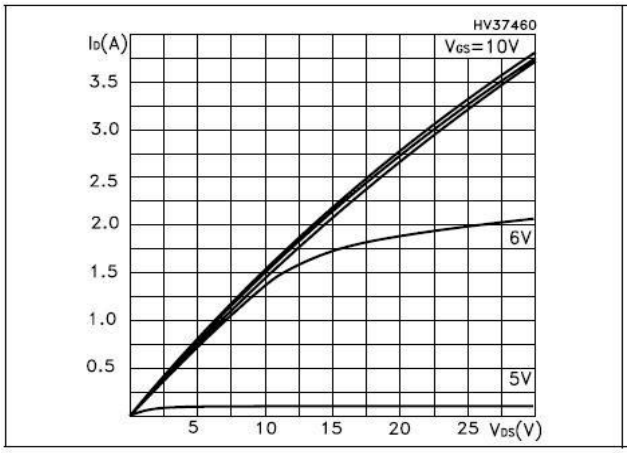


Figure 9. Transfer characteristics

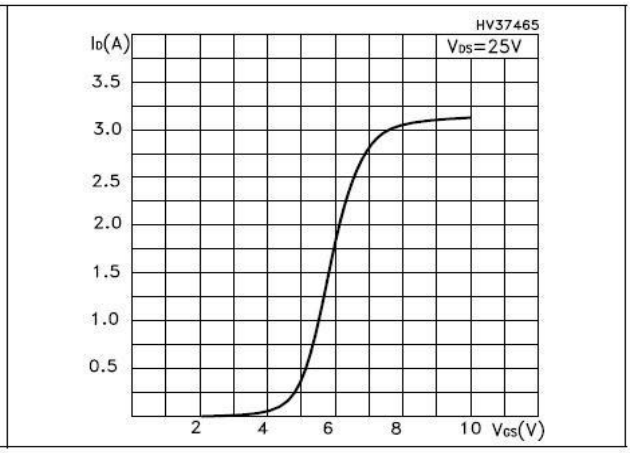


Figure 10. Normalized BV_{DSS} vs. temperature

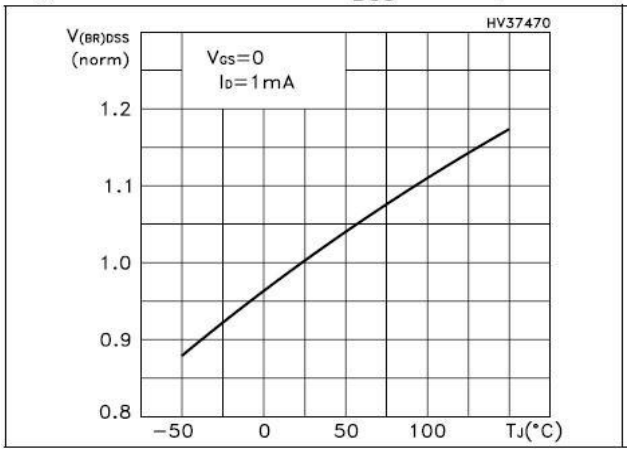


Figure 11. Static drain-source on resistance

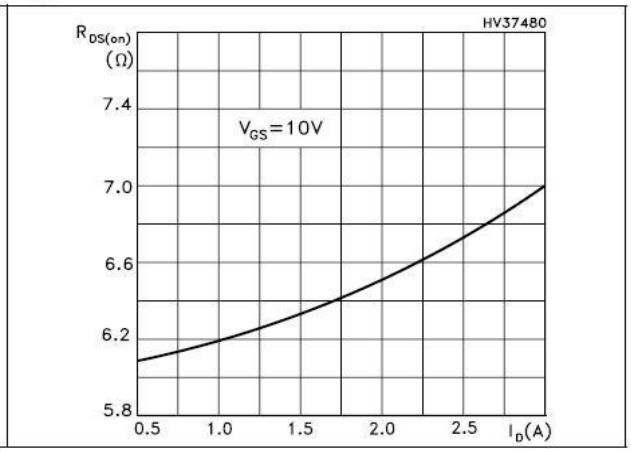


Figure 12. Gate charge vs. gate-source voltage

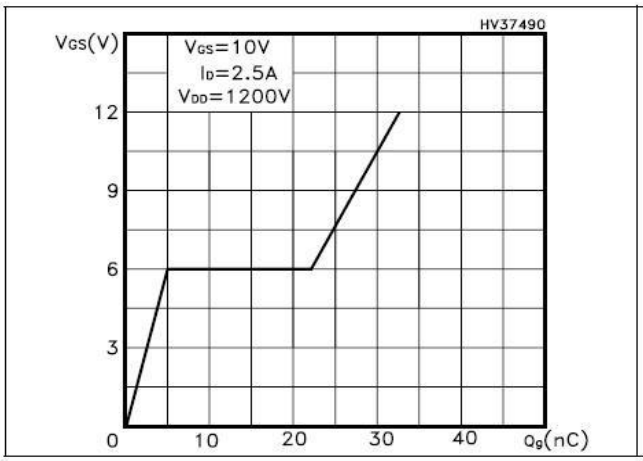


Figure 13. Capacitance variations

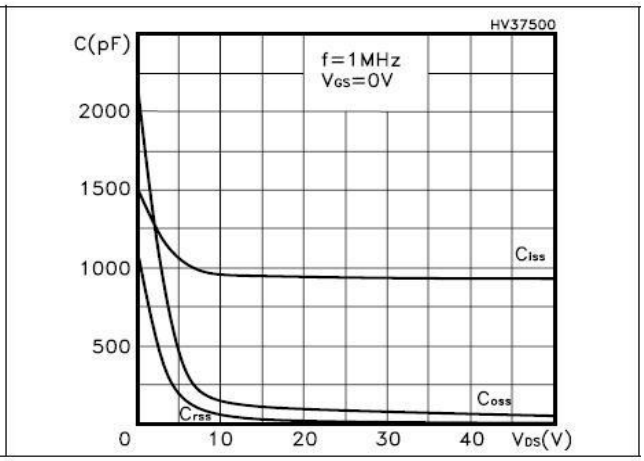


Figure 14. Normalized gate threshold voltage vs. temperature

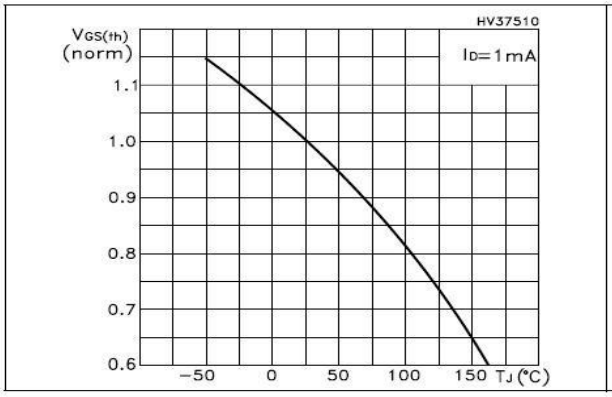


Figure 15. Normalized on resistance vs. temperature

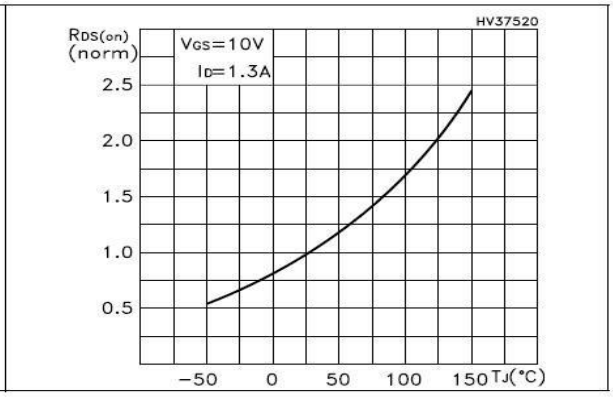


Figure 16. Source-drain diode forward characteristics

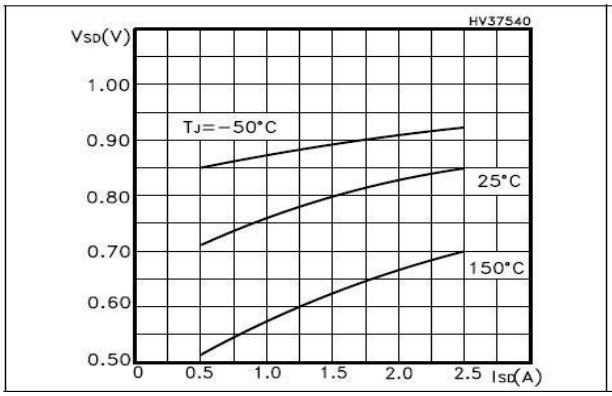
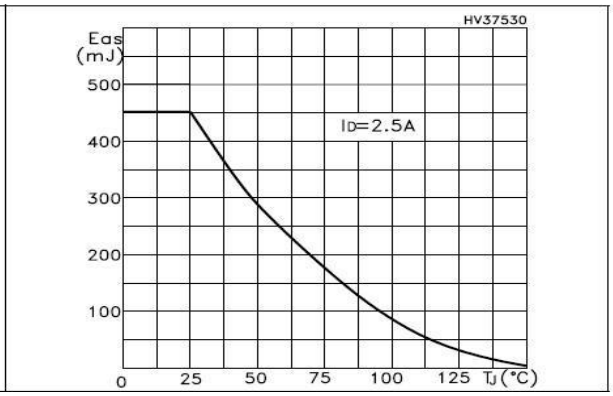


Figure 17. Maximum avalanche energy vs Tj



3 Test circuits

Figure 18. Switching times test circuit for resistive load

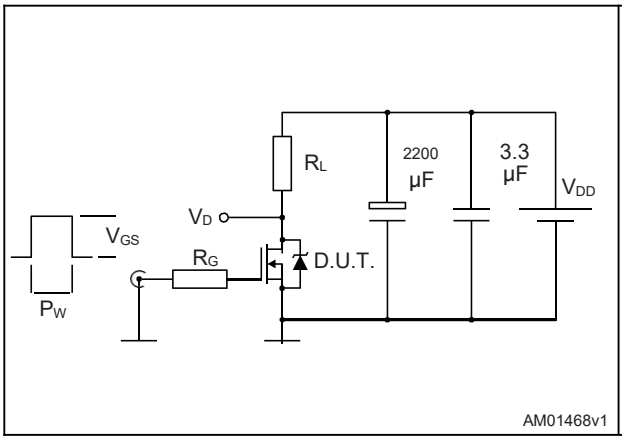


Figure 19. Gate charge test circuit

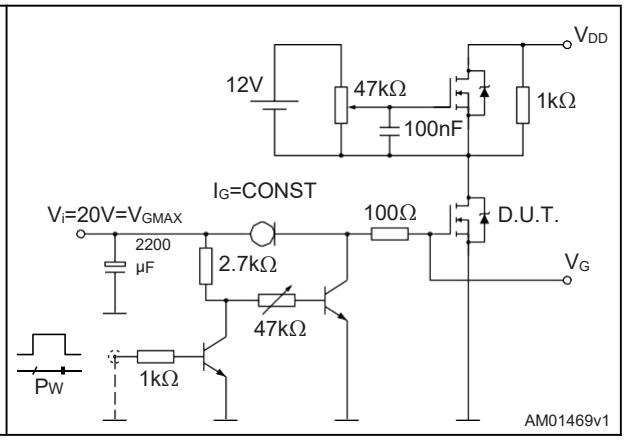


Figure 20. Test circuit for inductive load switching and diode recovery times

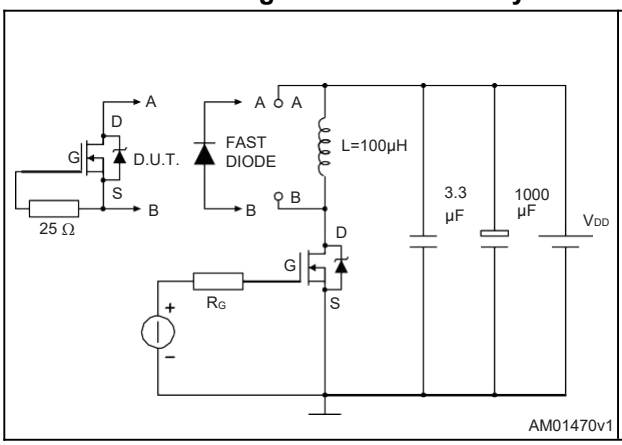


Figure 21. Unclamped inductive load test circuit

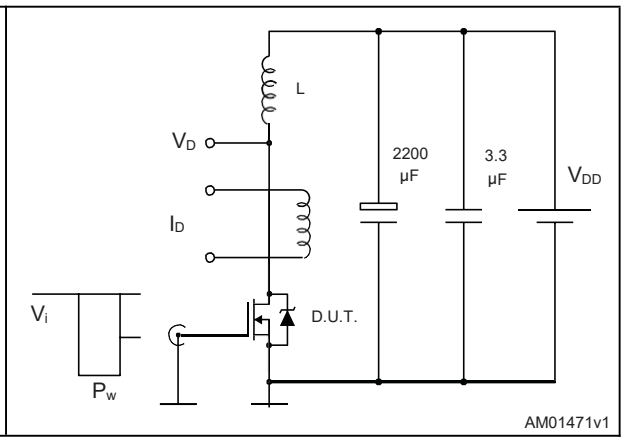


Figure 22. Unclamped inductive waveform

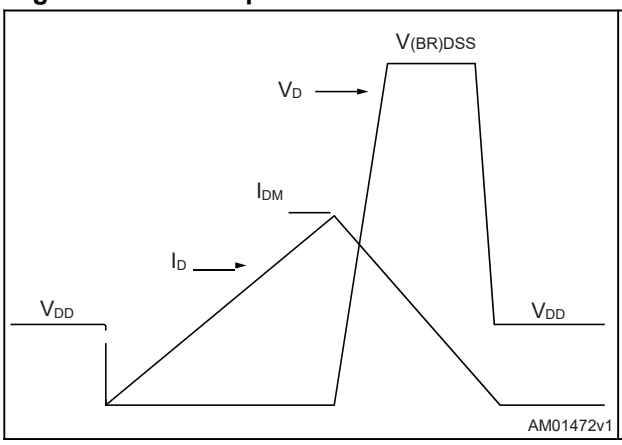
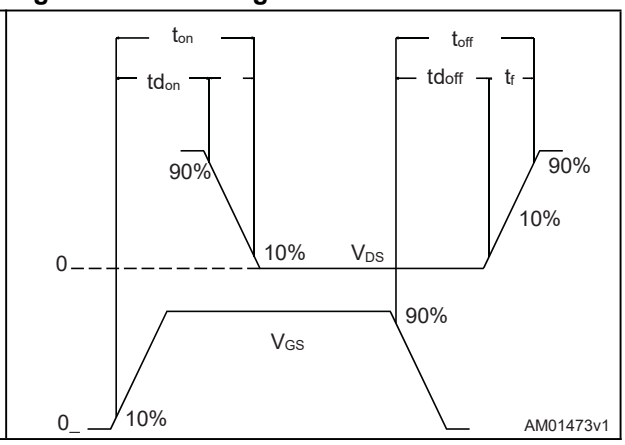


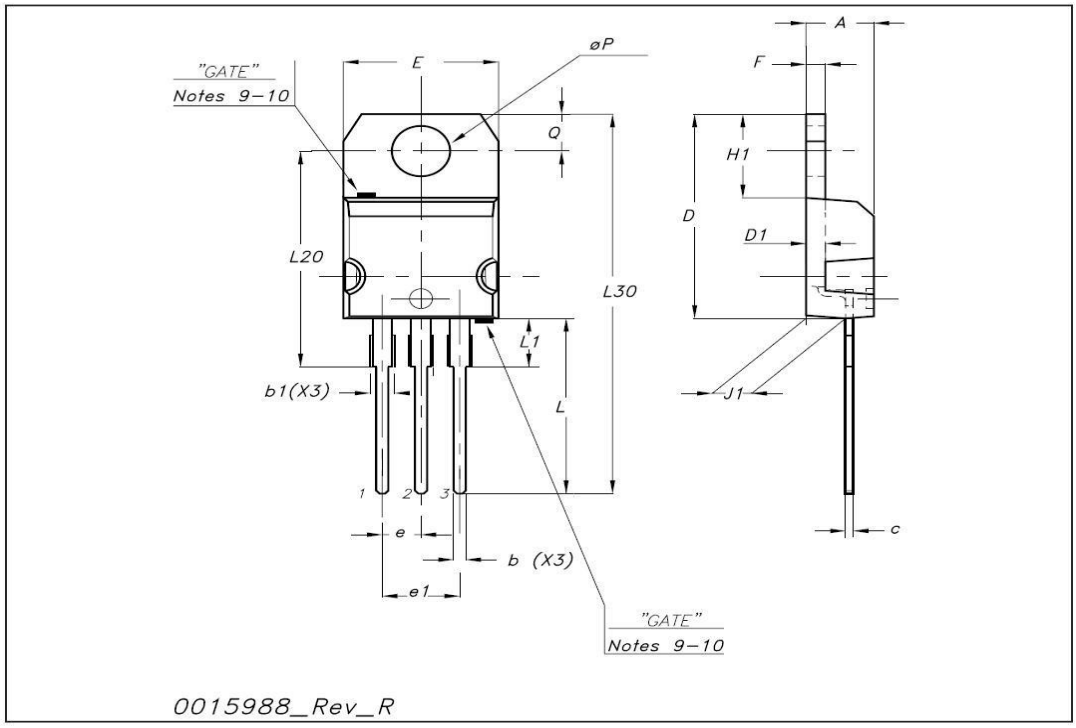
Figure 23. Switching time waveform



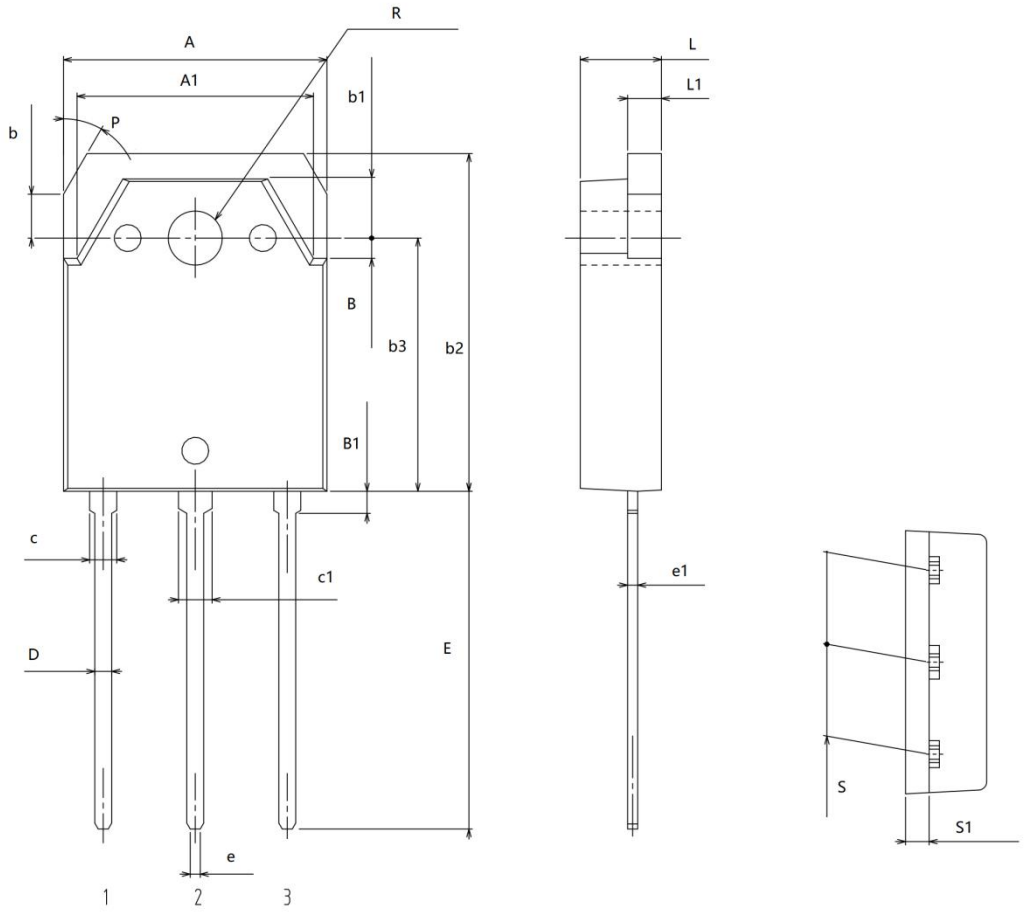
4 Package mechanical data

TO-220 mechanical data

Dim	mm			inch		
	Min	Typ	Max	Min	Typ	Max
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
c	0.48		0.70	0.019		0.027
D	15.25		15.75	0.6		0.62
D1		1.27			0.050	
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.051
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
∅P	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116

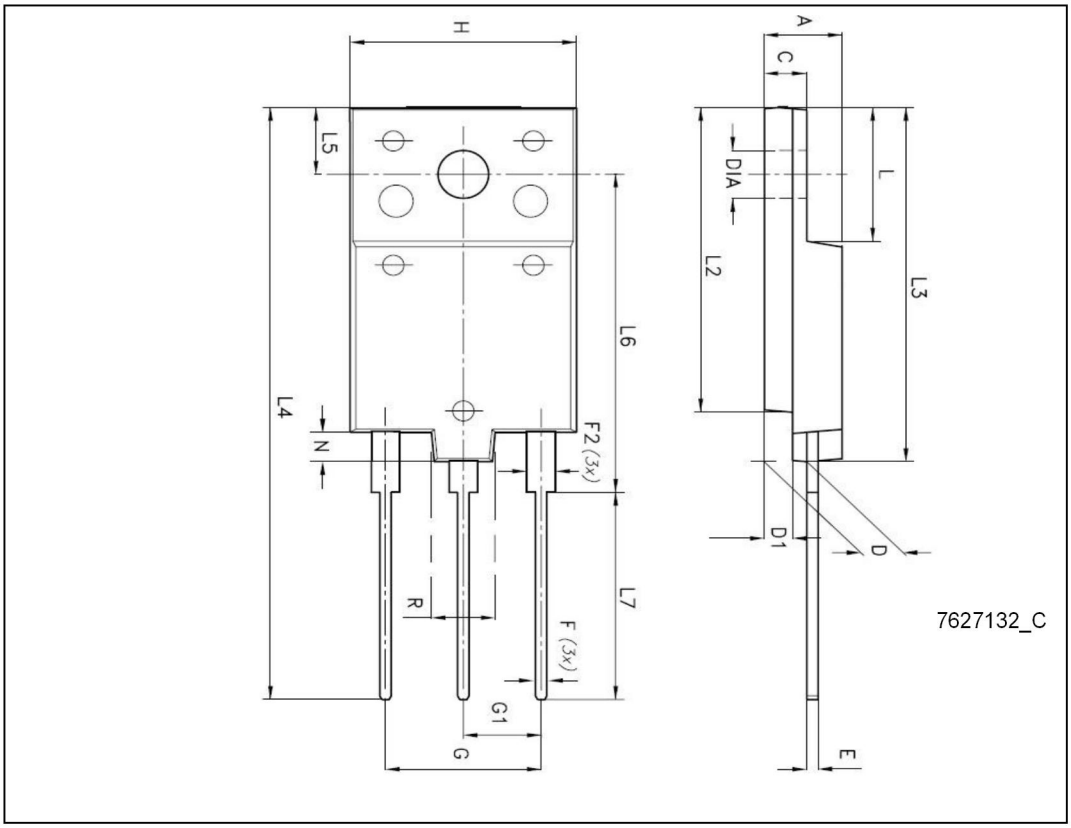


TO-3PB Mechanical data			
Dim	**mm.**		
	Min	**Typ**	**Max**
A	15.3	15.6	15.9
A1	13.8	14	14.2
b	2.4	2.6	2.8
b1	3.3	3.5	3.7
b2	19.7	20	20.3
b3	14.7	15	15.3
B	1	0.2	1.4
B1	1	1.3	1.6
c	1.3	1.6	1.9
c1	1.7	2	2.3
D	0.9	1	1.3
E	19.5	20	20.5
e	0.4	0.6	0.8
e1	-	0.6	-
L	4.6	4.8	5
L1	1.8	2	2.2
P		30°	
R	-	3.2	-
S	-	5.45	-
S1	-	1.41	-

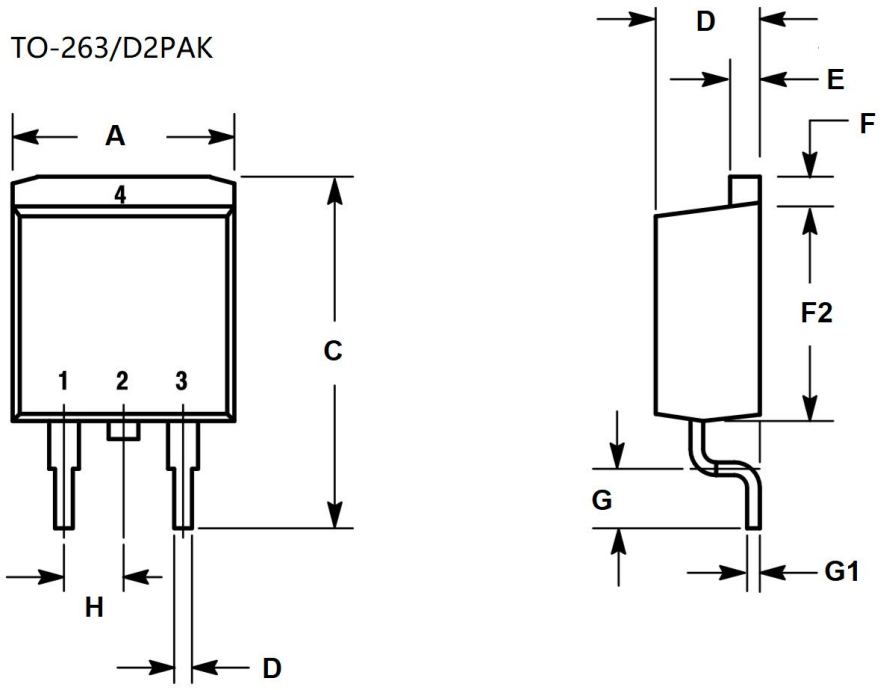


TO-3PF mechanical data

DIM.	mm.		
	min.	typ	max.
A	5.30		5.70
C	2.80		3.20
D	3.10		3.50
D1	1.80		2.20
E	0.80		1.10
F	0.65		0.95
F2	1.80		2.20
G	10.30		11.50
G1		5.45	
H	15.30		15.70
L	9.80	10	10.20
L2	22.80		23.20
L3	26.30		26.70
L4	43.20		44.40
L5	4.30		4.70
L6	24.30		24.70
L7	14.60		15
N	1.80		2.20
R	3.80		4.20
Dia	3.40		3.80



TO-263 mechanical data			
DIM.	mm.		
	min.	typ	max.
A	9.65		10.29
C	14.6		15.88
D	0.51		0.92
D1	4.06		4.83
E	1.14		1.40
F	1.14		1.40
F2	8.64		9.64
G	2.29		2.79
G1	0.46		0.64
H		2.54BSC	



TO-247 mechanical data

DIM.	mm.		
	min.	typ	max.
A	4.7		5.31
A1	2.21		2.59
A2	1.5		2.49
b	1		1.4
b2	1.65		2.39
b4	2.59		3.43
c	0.38		0.89
D	20.8		21.46
D1	13.08		-
D2	0.51		1.35
E	15.49		16.26
E1	13.46		-
E2	4.32		5.49
e	5.46BSC		
L	19.81		20.32
L1	-		4.5
P	3.56		3.66
Q	5.38		6.2
S	6.15BSC